PTO/SB/084(10-01)
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application Number	Unknown 10/756, 901				
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	First Named Inventor	Farrar, Paul				
	Group Art Unit	Unknown 2823				
	Examiner Name	Unknown Clark				
Sheet 1 of 2	Attorney Docket No: 3	303.572US2				

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	Group Art Unit	Unknown 2823			
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INFORMATION DISCLOSURE	Application Number	10/756,901
STATEMENT BY APPLICANT (Use as many shoeters belossely)	Filing Date	January 14, 2004
(20).	First Named Inventor	Farrar, Paul
NOV 1 4 2005	Group Art Unit	2823
100 14 2003	Examiner Name	Clark, Sheila
Sheet 1 of 1	Attorney Docket No: 3	303.572US2

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